

Material Declaration Report



Package Type:	DIP14
Pericom Package Code:	P14(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	1087.354
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10~20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	NA
Peak Body Temp (C):	260
Max Time (sec):	40
Reflow Cycles:	3
Rev Date:	Feb,05.2009

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	788.654	J	Silica	60676-860	70.90	559.15569
			Epoxy resin	29690-82-2	12.50	98.58175
			Phendic Resin(Handener)	9003-35-4	8.50	67.03559
			Brominated resin	Secret	1.50	11.82981
			Carbon Black	Secret	0.55	4.33760
			Wax	Secret	1.25	9.85818
			Flame Retardant	Secret	3.00	23.65962
			Catalyst	Secret	0.50	3.94327
			Stress Absorbent	Secret	0.30	2.36596
			Coupling Agent	Secret	0.50	3.94327
			Releasing Agent	Secret	0.50	3.94327
			LEAD FRAME	296.570		Cu
Fe	7439-89-6	0.73				2.15013
P	7723-14-0	3.20				9.49024
Zn	7440-66-6	0.18				0.51900
Pb	7439-92-1	5.36				15.89615
Silver	7440-22-4	--				--
TERMINATION PLATING	1.280		Tin	7440-31-5	99.90	1.27872
			Impurity	Proprietary	0.10	0.00128
SILICON DIE	0.350		Silicon	7440-21-3	99.763	0.34917
			Aluminum(Al)	7429-90-5	0.200	0.00070
			Copper(Cu)	7440-50-8	0.001	0.00000
			Titanium(Ti)	7440-32-6	0.028	0.00010
			Phosphorus(P)	7664-38-2	0.003	0.00001
			Boron(B)	7440-42-8	0.005	0.00002
DIE ATTACH EPOXY	0.220		Resin	Trade secret	15.00	0.03300
			Silver	7440-22-4	80.00	0.17600
			2-Butoxyethyl acetate	112-07-2	5.00	0.01100
GOLD WIRE	0.280		Au	7440-57-5	99.99	0.27997
			Other materials	Proprietary	0.01	0.00003

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<50	<2	<2	<2	<5	<5
Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<2	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	Declaration Statement:	Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium					
		Pb	Hg	Cr+6	Cd	PBB	PBDE
	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	
	O	O	O	O	O	O	

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.
X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.